

# DATA SHEET



## **BCX71 series** PNP general purpose transistors

Product data sheet  
Supersedes data of 1999 Apr 20

2004 Feb 16

# PNP general purpose transistors

# BCX71 series

### FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 45 V)
- Low noise.

### APPLICATIONS

- Low level, low noise, low frequency applications in hybrid circuits
- General purpose switching and amplification.

### DESCRIPTION

PNP transistor in a plastic SOT23 package.  
NPN complements: BCX70 series.

### MARKING

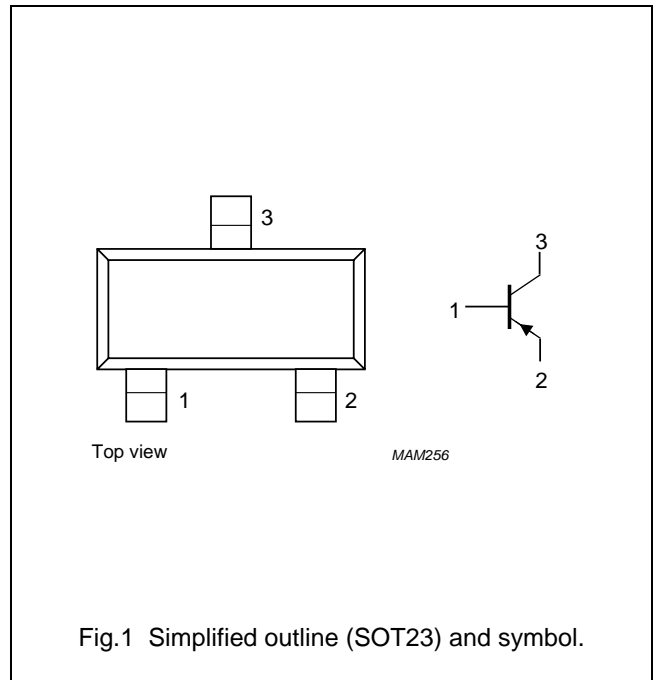
TYPE NUMBER	MARKING CODE <sup>(1)</sup>
BCX71H	BH*
BCX71J	BJ*
BCX71K	BK*

### Note

- \* = p : Made in Hong Kong.  
\* = t : Made in Malaysia.  
\* = W : Made in China.

### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BCX71H	-	plastic surface mounted package; 3 leads	SOT23
BCX71J			
BCX71K			

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## BCX71 series

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	–	–45	V
V <sub>CEO</sub>	collector-emitter voltage	open base	–	–45	V
V <sub>EBO</sub>	emitter-base voltage	open collector	–	–5	V
I <sub>C</sub>	collector current (DC)		–	–100	mA
I <sub>CM</sub>	peak collector current		–	–200	mA
I <sub>BM</sub>	peak base current		–	–200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	–	250	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–	150	°C
T <sub>amb</sub>	operating ambient temperature		–65	+150	°C

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	500	K/W

**Note**

1. Transistor mounted on an FR4 printed-circuit board.

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## BCX71 series

**CHARACTERISTICS**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CBO}$	collector-base cut-off current	$I_E = 0; V_{CB} = -45\text{ V}$	–	–	–20	nA
		$I_E = 0; V_{CB} = -45\text{ V}; T_{amb} = 150\text{ °C}$	–	–	–20	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$I_C = 0; V_{EB} = -4\text{ V}$	–	–	–20	nA
$h_{FE}$	DC current gain BCX71H BCX71J BCX71K	$I_C = -10\text{ }\mu\text{A}; V_{CE} = -5\text{ V}$	30	–	–	
			40	–	–	
			100	–	–	
	DC current gain BCX71H BCX71J BCX71K	$I_C = -2\text{ mA}; V_{CE} = -5\text{ V}$	180	–	310	
			250	–	460	
			380	–	630	
	DC current gain BCX71H BCX71J BCX71K	$I_C = -50\text{ mA}; V_{CE} = -1\text{ V}; \text{note 1}$	80	–	–	
			100	–	–	
			110	–	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.25\text{ mA}$	–60	–	–250	mV
		$I_C = -50\text{ mA}; I_B = -1.25\text{ mA}; \text{note 1}$	–120	–	–550	mV
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.25\text{ mA}$	–600	–	–850	mV
		$I_C = -50\text{ mA}; I_B = -1.25\text{ mA}; \text{note 1}$	–680	–	–1050	mV
$V_{BE}$	base-emitter voltage	$I_C = -2\text{ mA}; V_{CE} = -5\text{ V}$	–600	–650	–750	mV
		$I_C = -10\text{ }\mu\text{A}; V_{CE} = -5\text{ V}$	–	–550	–	mV
		$I_C = -50\text{ mA}; V_{CE} = -1\text{ V}; \text{note 1}$	–	–720	–	mV
$C_c$	collector capacitance	$I_E = I_e = 0; V_{CB} = -10\text{ V}; f = 1\text{ MHz}$	–	4.5	–	pF
$C_e$	emitter capacitance	$I_C = I_c = 0; V_{EB} = -0.5\text{ V}; f = 1\text{ MHz}$	–	11	–	pF
$f_T$	transition frequency	$I_C = -10\text{ mA}; V_{CE} = -5\text{ V}; f = 100\text{ MHz}$	100	–	–	MHz
F	noise figure	$I_C = -200\text{ }\mu\text{A}; V_{CE} = -5\text{ V}; R_S = 2\text{ k}\Omega;$ $f = 1\text{ kHz}; B = 200\text{ Hz}$	–	2	6	dB

**Note**

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .

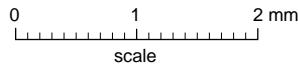
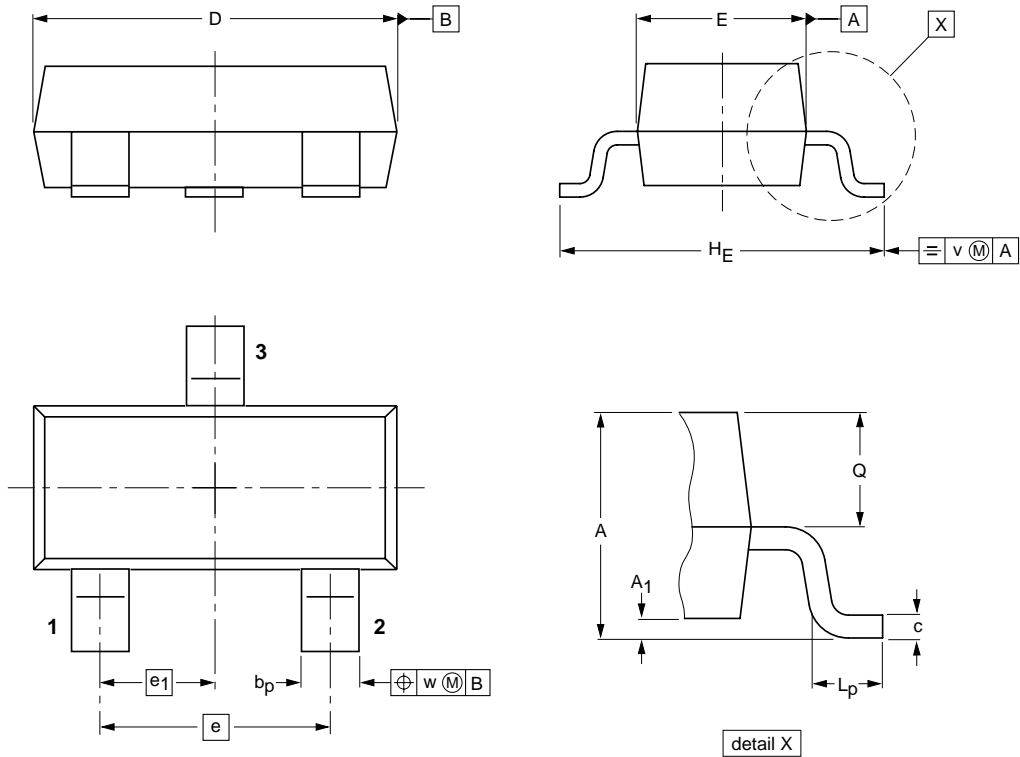
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PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max.	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				04-11-04 06-03-16

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## BCX71 series

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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# ***NXP Semiconductors***

## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

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